WHAT IS CLAIMED IS:

1. A carrier for receiving and electrically contacting individually separated dies for the testing and/or burn-in of the same, wherein the carrier comprises:

a support structure;

first contacts disposed on the support structure and arranged in a grid pattern corresponding to a die to be contacted;

elastomer bumps provided on the first contacts;

second contacts formed on the elastomer bumps, wherein the second contacts are electrically connected to the first contacts; and

at least one opening in the support structure wherein dies placed on the support structure can be drawn against the elastomer bumps by a force generated by a vacuum and applied through the opening.

2. The carrier of claim 1 wherein the second contacts are comprised of gold.

3. The carrier of claim 1 wherein the electrical connection of the first contacts to the second contacts is established by conductor tracks rising on the elastomer bumps in a spiral or arcuate manner to a tip of the elastomer bump.

4. The carrier of claim 3 wherein the conductor tracks comprise a copper-nickel-gold layer construction.

5. The carrier of claim 1 wherein a gold-gold contact is realized between the die and the carrier by a re-distribution layer arranged on the die.

1 6. The carrier of claim 1 wherein the re-distribution layer comprises a copper-nickel-gold
2 layer construction.

1 7. The carrier of claim 1 and further comprising a cover overlying the support structure.

1 8. The carrier of claim 7 wherein the cover is formed as a spring element.

9. A method of processing a semiconductor die, the method comprising:

providing a semiconductor die, the die including contacts formed in a pattern;

providing a carrier, the carrier comprising first contacts disposed over a surface of a support structure, elastomer bumps provided on the first contacts, and second contacts formed on the elastomer bumps, wherein the second contacts are arranged in a pattern corresponding to the pattern on the die, the second contacts being electrically coupled to the first contacts;

placing the die on the support structure of the carrier;

securing the contacts of the die against the elastomer bumps by a predetermined force generated by a vacuum; and

evaluating the semiconductor die.

10. The method of claim 9 wherein the die is fixed until the contacts of the die are secured against the elastomer bumps.

11. The method of claim 10 wherein the fixing of the die takes place by a cover, wherein the cover compresses the elastomer bumps with a predetermined pressing force after placing.

12. The method of claim 11 wherein the pressing force is approximately 2 to 8 grams per elastomer bump.

13. The method of claim 11 wherein the cover is formed as a spring element.

14. The method of claim 9 wherein providing a semiconductor die comprises:

fabricating a wafer that includes a plurality of semiconductor dies; and

separating the wafer to provide the semiconductor die.

15. The method of claim 9 wherein evaluating the semiconductor die comprises testing the semiconductor die.

16. The method of claim 9 wherein evaluating the semiconductor die comprises burning-in the semiconductor die.

17. The method of claim 9 wherein the second contacts of the carrier are comprised of gold.

18. The method of claim 9 wherein the electrical connection of the first contacts to the second contacts is established by conductor tracks rising on the elastomer bumps in a spiral or arcuate manner to the tip.

19. The carrier of claim 18 wherein the conductor tracks comprise a copper-nickel-gold layer construction.

20. The carrier of claim 9 wherein a gold-gold contact is realized between the die and the carrier by re-distribution layers being arranged on the die, and wherein the re-distribution layers comprise a copper-nickel-gold layer construction.